

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously Presented) A compression assembled semiconductor package comprising:

- a semiconductor die having a first major surface and a second major surface;
- a control electrode disposed on a first major surface of said semiconductor die, and first and second electrodes disposed on first and second major surfaces respectively of said semiconductor die;
- a molded plastic insulation ring annularly disposed around said semiconductor die;
- a control signal carrier extending through said molded insulation ring from the exterior thereof and electrically connected to said control electrode;
- a first pole being in surface-to-surface electrical contact with said first electrode; and
- a second pole being in surface-to-surface electrical contact with said second electrode,

whereby said semiconductor die is held in place between said first pole and said second pole;

wherein said first pole comprises and forms a unitary body with a rim, said rim being ultrasonically bonded directly to an end of said molded plastic insulation ring.

2-4. (Canceled)

5. (Original) The compression assembled semiconductor package of claim 1, wherein said first pole includes a groove to allow said control signal carrier to reach said control electrode.

6. (Original) The compression assembled semiconductor package of claim 1, wherein said semiconductor die is a thyristor.

7. (Original) The compression assembled semiconductor package of claim 1, wherein said first pole includes a connection tab extending radially away from its periphery.

8-9. (Canceled)

10. (Original) The compression assembled semiconductor package of claim 1, wherein said control signal carrier comprises a control pin in electrical contact at one end thereof with said control electrode and electrically connected by a conductive strip to a lead that extends through the body of said molded plastic insulation ring.

11. (Canceled)

12. (Previously Presented) A compression assembled semiconductor package comprising:

- a semiconductor die having a first major surface and a second major surface;

- a control electrode disposed on a first major surface of said semiconductor die, and first and second electrodes disposed on first and second major surfaces respectively of said semiconductor die;

- a molded plastic insulation ring annularly disposed around said semiconductor die;

- a control signal carrier extending through said molded insulation ring from the exterior thereof and electrically connected to said control electrode;

- a first pole being in surface-to-surface electrical contact with said first electrode; and

- a second pole being in surface-to-surface electrical contact with said second electrode,

whereby said semiconductor die is held in place between said first pole and said second pole,

wherein said second pole comprises and forms a unitary body with a rim, said rim being ultrasonically bonded directly to an end of said molded plastic insulation ring.

13-25 Canceled.